

PATENT APPLICATION *IFW*

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 7, 2008

Applicants: Atsushi YABE et al

Title: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231

Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006

Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

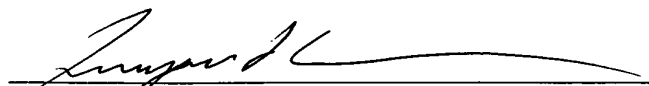
☐ Applicant claims small entity status. See 37 CFR 1.27.☐ The additional filing fee has been calculated as shown below:

| For                          | No.<br>Filed | No.<br>Extra | (X)<br>LG Entity | RATE     | ( )<br>SM Entity | Fee      |
|------------------------------|--------------|--------------|------------------|----------|------------------|----------|
| Total Claims                 | (4 - 20 = 0) |              | x                | \$ 50.00 | x                | \$ 25.00 |
| Indep. Claims                | (1 - 3 = 0)  |              | x                | \$210.00 | x                | \$105.00 |
| [ ] Multiple Dep. Claim      |              |              | +                | \$370.00 | +                | \$185.00 |
| * * * TOTAL FILING FEE * * * |              |              |                  |          |                  | \$ 0.00  |

☐ Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.☐ A Check for \$ is enclosed to cover fees.☒ Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

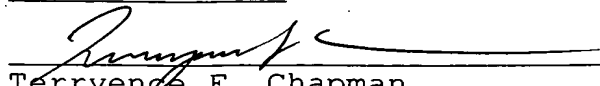
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TFC/smd

  
Terryence F. Chapman Reg. No. 32 549-----  
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130.09/07

  
Terryence F. Chapman



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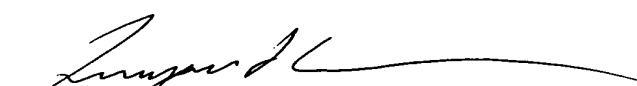
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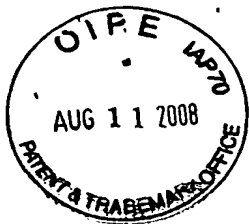
  
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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

Sir:

In response to the Office Action dated May 9, 2008,  
please amend the above-identified application as follows:  
(Please see following pages.)

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